TOSHIBA CRS02

TOSHIBA SCHOTTKY BARRIER RECTIFIER TRENCH SCHOTTKY BARRIER TYPE

CRS02

SWITCHING TYPE POWER SUPPLY APPLICATIONS

PORTABLE EQUIPMENT BATTERY APPLICATIONS

Low Forward Voltage : $V_{FM} = 0.40 \text{ V (Max.)}$

Average Forward Current : $I_{F(AV)} = 1.0 A$

Repetitive Peak Reverse Voltage : $V_{RRM} = 30 V$

Small & Thin Package : S-FLAT (Toshiba Package Name)

MAXIMUM RATINGS

CHARACTERISTIC	SYMBOL	RATING	UNIT	
Repetitive Peak Reverse Voltage	v_{RRM}	30	V	
Average Forward Current	I _{F (AV)}	1.0	Α	
Peak One Cycle Surge Forward Current (Non-Repetitive)	I_{FSM}	20 (50 Hz)	A	
Junction Temperature	T_{j}	-40~125	°C	
Storage Temperature Range	$\mathrm{T_{stg}}$	-40~125	°C	

Unit in mm 3.5 ± 0.2 2.6 ± 0.1 0.9 ± 0.1 0.16 1.6 +0.2 1. ANODE 2. CATHODE **JEDEC EIAJ TOSHIBA** 3-2A1A

Weight: 0.013 g

ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Peak Forward Voltage V _F	$V_{\mathrm{FM}(1)}$	$I_{FM} = 0.1 A$	_	0.27	_	V
	$V_{\mathrm{FM}(2)}$	$I_{FM} = 0.7 A$	_	0.36	0.40	V
	$V_{\mathrm{FM}(3)}$	$I_{FM} = 1.0 A$	_	0.40	-	V
Repetitive Peak Reverse Current	I _{RRM}	$V_{RRM} = 30 V$	_	_	50	μ A
Junction Capacitance	C_{j}	$V_{R} = 10 \text{ V, f} = 1.0 \text{ MHz}$		40	_	pF
Thermal Resistance R _{th (j-a)}	On ceramic substrate	_	_	70	°C/W	
	tth (j-a)	On glass-epoxy substrate	_		140] C/ W [

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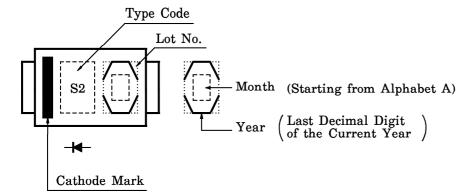
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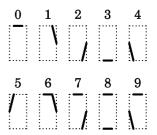
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MARKING



FOLLOWING INDICATES THE DATE OF MANUFACTURE



STANDARD SOLDERING PAD

Unit: mm

